

SNAS547C - FEBRUARY 1995 - REVISED APRIL 2013

LM384 5W Audio Power Amplifier

Check for Samples: LM384

FEATURES

- Wide Supply Voltage Range: 12V to 26V
- Low Quiescent Power Drain
- Voltage Gain Fixed at 50
- High Peak Current Capability: 1.3A
- Input Referenced to GND
- High Input Impedance: 150kΩ
- Low Distortion: 0.25% (P₀=4W, R_L=8Ω)
- Quiescent Output Voltage is at One Half of the Supply Voltage
- 14-Pin PDIP Package

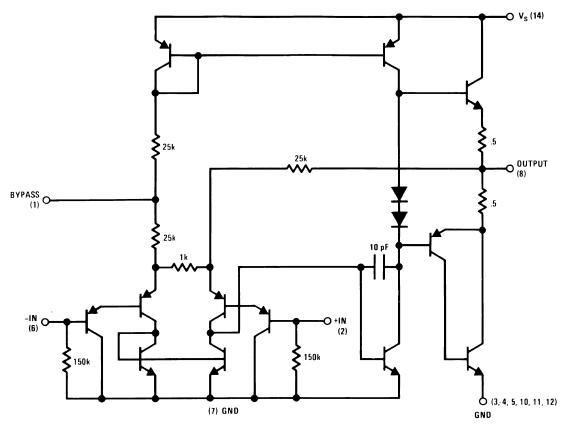
DESCRIPTION

The LM384 is a power audio amplifier for consumer applications. In order to hold system cost to a minimum, gain is internally fixed at 34 dB. A unique input stage allows ground referenced input signals. The output automatically self-centers to one-half the supply voltage.

The output is short-circuit proof with internal thermal limiting. The package outline is standard dual-in-line. A copper lead frame is used with the center three pins on either side comprising a heat sink. This makes the device easy to use in standard p-c layout.

Uses include simple phonograph amplifiers, intercoms, line drivers, teaching machine outputs, alarms, ultrasonic drivers, TV sound systems, AM-FM radio and sound projector systems. See SNAA086 for circuit details.





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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾

Supply Voltage	28V	
Peak Current		1.3A
Power Dissipation ⁽³⁾⁽⁴⁾		1.67W
Input Voltage		±0.5V
Storage Temperature	−65°C to +150°C	
Operating Temperature	0°C to +70°C	
Lead Temperature (Soldering, 10 sec.)	260°C	
Thermal Resistance	θ _{JC}	30°C/W
	θ_{JA}	79°C/W

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and (2)specifications.

The maximum junction temperature of the LM384 is 150°C. (3)

(4) The package is to be derated at 15°C/W junction to heat sink pins.

Electrical Characteristics⁽¹⁾

Symbol Parameter		Conditions	Min	Тур	Max	Units	
Z _{IN}	Input Resistance			150		kΩ	
I _{BIAS}	Bias Current	Inputs Floating		100		nA	
A _V	Gain		40	50	60	V/V	
P _{OUT}	Output Power	THD = 10%, $R_L = 8\Omega$	5	5.5		W	
l _Q	Quiescent Supply Current			8.5	25	mA	
V _{OUT Q}	Quiescent Output Voltage			11		V	
BW	Bandwidth	$P_{OUT} = 2W, R_L = 8\Omega$		450		kHz	
V ⁺	Supply Voltage		12		26	V	
I _{SC}	Short Circuit Current ⁽²⁾			1.3		А	
PSRR _{RTO}	Power Supply Rejection Ratio ⁽³⁾			31		dB	
THD	Total Harmonic Distortion	$P_{OUT} = 4W, R_L = 8\Omega$		0.25	1.0	%	

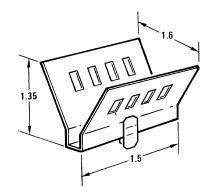
 V^+ = 22V and T_A = 25°C operating with a Staver V7 heat sink for 30 seconds. (1)

Output is fully protected against a shorted speaker condition at all voltages up to 22V. Rejection ratio referred to the output with $C_{BYPASS} = 5 \ \mu\text{F}$, freq = 120 Hz. (2)

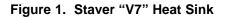
(3)



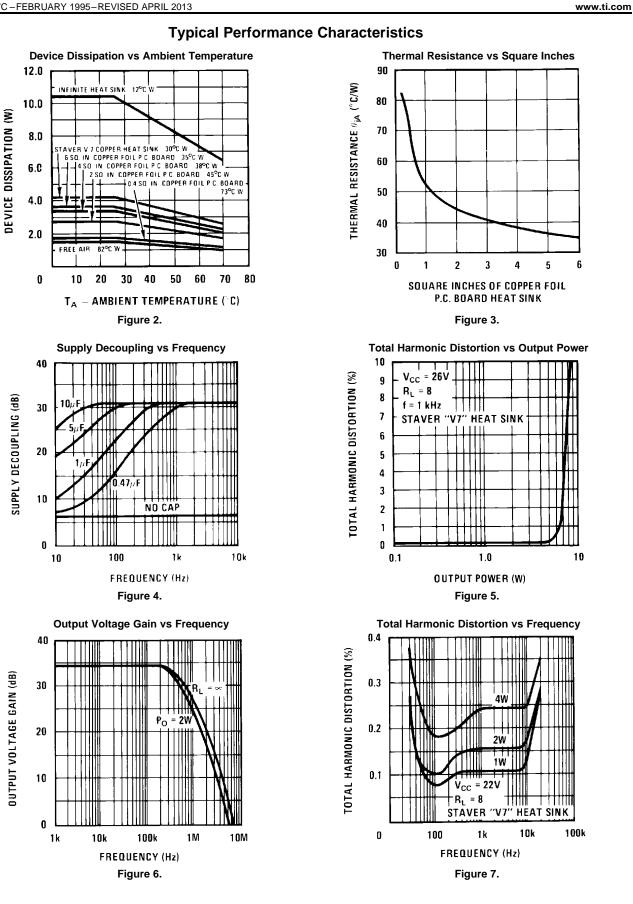
Heat Sink Dimensions



Staver Company 41 Saxon Ave. P.O. Drawer H Bay Shore, N.Y. Tel: (516) 666-8000

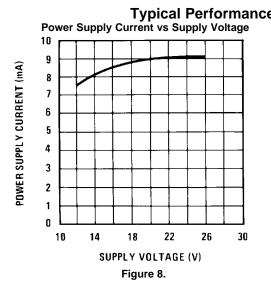


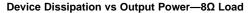


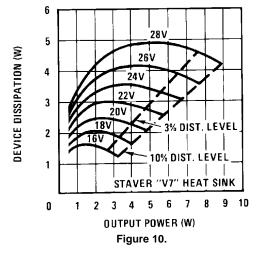


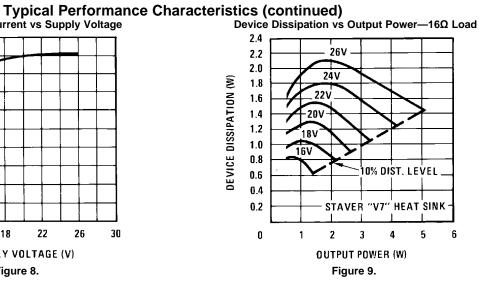
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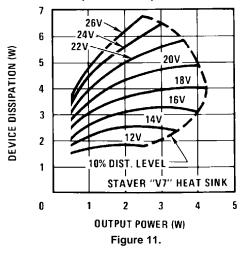






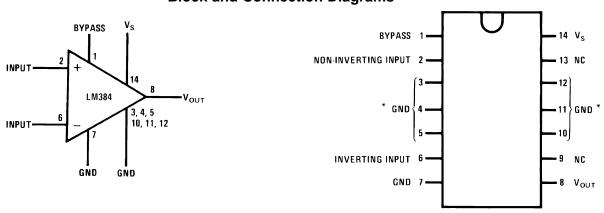


Device Dissipation vs Output Power-4Ω Load





Block and Connection Diagrams



Note: Heatsink Pins

Figure 12. 14-Pin PDIP (Top View) See NFF0014A Package

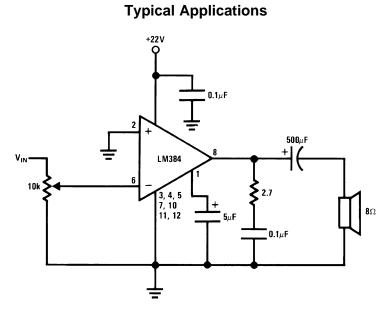
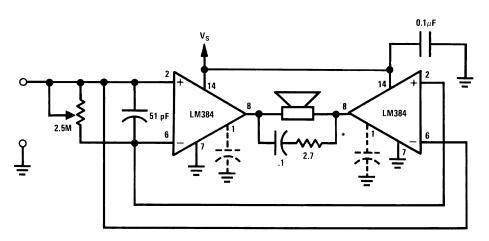


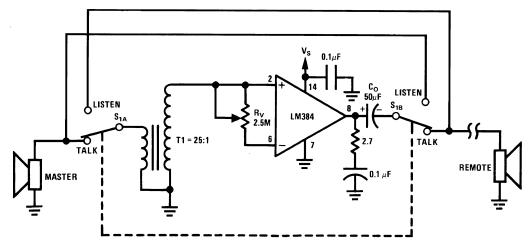
Figure 13. Typical 5W Amplifier



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^{*}For stability with high current loads

Figure 15. Intercom

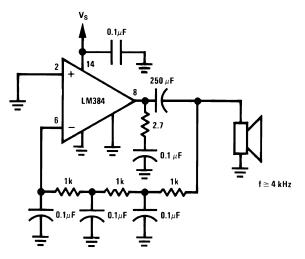


Figure 16. Phase Shift Oscillator

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C	hanges from Revision B (April 2013) to Revision C	Page		
•	Changed layout of National Data Sheet to TI format	7		

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM384N/NOPB	ACTIVE	PDIP	NFF	14	25	Green (RoHS & no Sb/Br)	SN	Level-1-NA-UNLIM	0 to 70	LM384N	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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MECHANICAL DATA

NFF0014A





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